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Silicon nitride ceramic substrates

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Foreword

This document is in accordance with the provisions of GB/T 1.1-2020 "Guidelines for standardization work Part 1: Structure and drafting rules for standardization documents" Drafting.

Please note that some of the contents of this document may involve patents. The issuing organization of this document does not assume the responsibility for identifying patents.

This document is proposed by China Building Materials Federation.

This document is under the jurisdiction of the National Technical Committee for Standardization of Industrial Ceramics (SAC/TC194).

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Silicon nitride ceramic substrate

1 Scope

This document specifies the product classification and marking, technical requirements, test methods, inspection rules, marking, packaging, transportation, etc. of silicon nitride ceramic substrates. and storage.

This document is applicable to silicon nitride ceramic substrates for power semiconductor modules and can be used as a reference for silicon nitride ceramic substrates for other functions.

2 Normative references

GB/T 191

GB/T 1408.1

GB/T 2828.1

GB/T 5594.4

GB/T 5594.5

GB/T 6062

GB/T 9530

GB/T 10700

GB/T 14619-2013

GB/T 16534

GB/T 16535

GB/T 16555

GB/T 17991

GB/T 22588

GB/T 25995

GB/T 39975-2021

GB/T 41605

GB/T 45763

3 Terms and Definitions

The terms and definitions defined in GB/T 9530 and GB/T 17991 and the following apply to this document.

3.1

A sheet-like silicon nitride ceramic support on which conductor patterns, membrane elements, or electronic components can be printed.

Note. Hereinafter referred to as substrate.